GUC

The Advanced ASIC Leader

About GUC

Global Unichip Corp. (GUC) provides advanced ASIC solutions for computing, communications, and consumer electronics. TSMC, GUC's largest shareholder and key partner, empowers GUC with cutting-edge process and packaging technologies.

Global Presence

- Headquartered in Taiwan, with a global footprint across North America, China, Europe, Japan, Korea, and Vietnam.
- Over 800 professionals worldwide.

Our Leadership

- Expertise in advanced process and packaging technologies (APT).
- 600+ production-proven projects.
- Member of TSMC's IPA, DCA, VCA, and 3D Fabric Alliance.

Flexible Business Models

- Fulfill customers' most demanding requirements.
- Adaptable engagement models for diverse needs.

Customer Requirements

Spec-In	Netlist-In	GDS-In	Mask-In	Logistics
System SoC	Chip Implementation	Mask Making & Wafer Processing	Packaging & Testing	

Custom Design Solutions

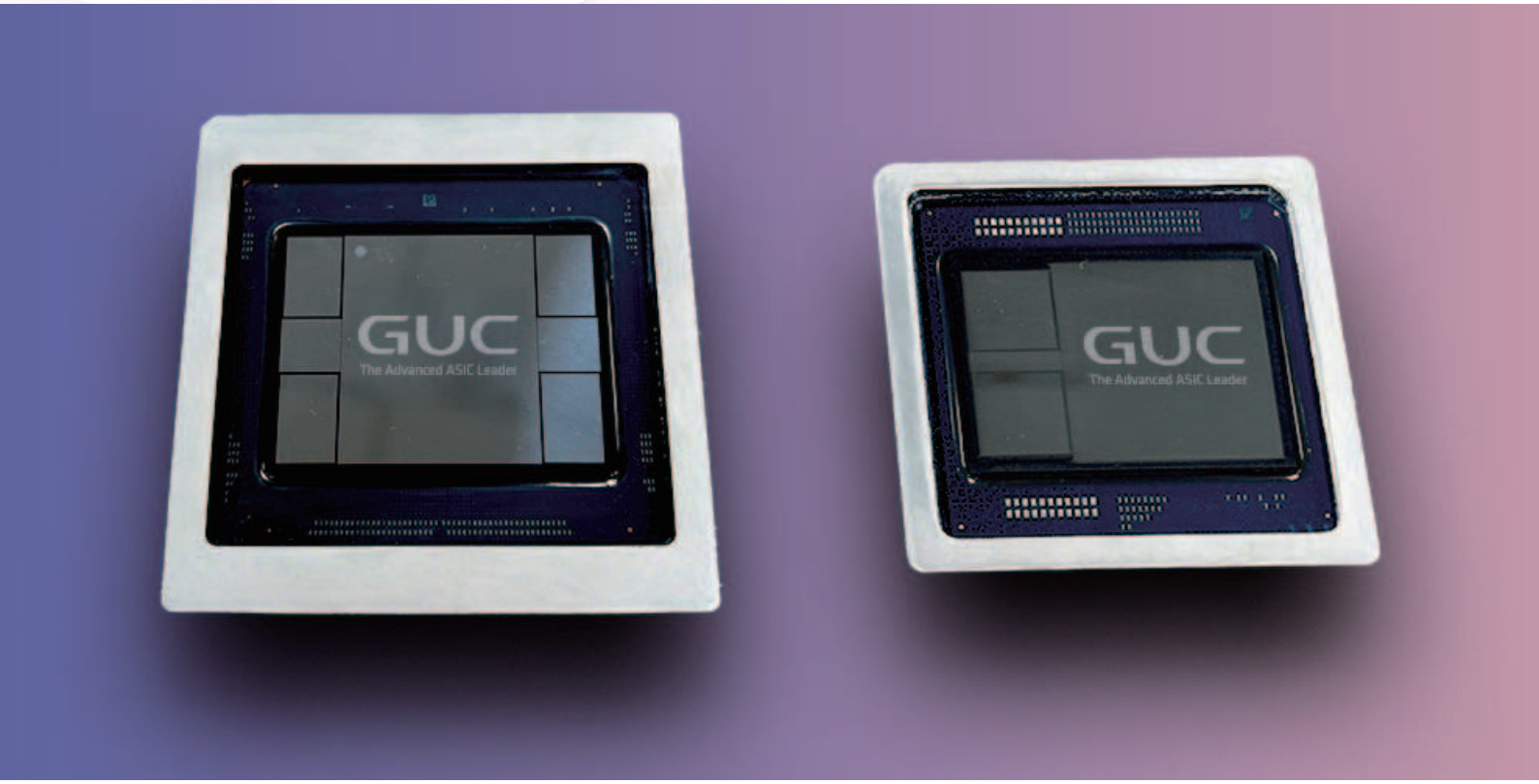
- Comprehensive services include architecture, IP solutions, sub-system integration, verification, software, system emulation, physical design, and GDSII delivery.
- Operations team ensures rapid production ramp with enhanced package design, testing, and manufacturing logistics.
- Customizable in-house APT IPs (HBM, UCIe-A/GLink-2.5D, UCIe-3D/GLink-3D) for high-bandwidth, low-power 2.5D/3D designs.

2.5D/3D Design Expertise

- Collaborative solutions with ecosystem partners.
- Extensive experience with TSMC's CoWoS, InFO, and SoIC technologies.
- Advanced SI, PI, IR, thermal, and mechanical design capabilities.
- Flagship APT IP portfolio:
  - HBM PHY & Controller IP family.
  - Die-to-Die IP (UCIe-A/GLink-2.5D) for 2.5D designs.
  - Die-on-Die IP (UCIe-3D/GLink-3D) for 3D SoIC designs.
- Utilizing 2.5D and 3D expertise to deliver holistic solutions.

Pioneering 2nm ASIC Design Technology

- Advanced 2nm design solutions ready.
- Achieved N2P tape-out in Sep'24.



What We Do

- GUC leads the way among ASIC design service providers, excelling in key segments such as artificial intelligence (AI), high-performance computing (HPC), 5G networking, automotive, storage, and various industrial applications.
- We are committed to delivering highly competitive designs that optimize power, performance, and area (PPA) while maintaining exceptional quality and yield. Our focus on engineering excellence ensures unparalleled value for our customers.